TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (High-Speed U-MOS III)

# **TPC8016-H**

High-Efficiency DC / DC Converter Applications Notebook PC Applications Portable-Equipment Applications

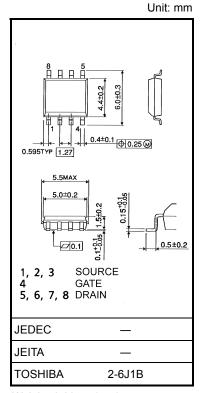
- Small footprint due to small and thin package
- High-speed switching
- Small gate charge: Qg = 48 nc (typ.)
- Low drain-source ON-resistance:  $R_{DS}$  (ON) = 3.7 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 25 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$
- Enhancement mode:  $V_{th} = 1.1 \text{ to } 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

#### Maximum Ratings (Ta = 25°C)

| Characte              | eristic                         | Symbol           | Rating     | Unit |  |
|-----------------------|---------------------------------|------------------|------------|------|--|
| Drain-source voltage  |                                 | $V_{DSS}$        | 30         | V    |  |
| Drain-gate voltage (R | $R_{GS} = 20 \text{ k}\Omega$ ) | $V_{DGR}$        | 30         | V    |  |
| Gate-source voltage   |                                 | $V_{GSS}$        | ±20        | V    |  |
| Drain current         | DC (Note 1)                     | I <sub>D</sub>   | 15         | Α    |  |
| Diam current          | Pulsed (Note 1)                 | $I_{DP}$         | 60         | ζ    |  |
| Drain power dissipati | on $(t = 10 s)$<br>(Note 2a)    | $P_{D}$          | 1.9        | W    |  |
| Drain power dissipati | on (t = 10 s)<br>(Note 2b)      | P <sub>D</sub>   | 1.0        | W    |  |
| Single-pulse avalance | he energy<br>(Note 3)           | E <sub>AS</sub>  | 146        | mJ   |  |
| Avalanche current     |                                 | I <sub>AR</sub>  | 15         | Α    |  |
| Repetitive avalanche  | energy<br>Note 2a) (Note 4)     | E <sub>AR</sub>  | 0.19       | mJ   |  |
| Channel temperature   | :                               | T <sub>ch</sub>  | 150        | °C   |  |
| Storage temperature   | range                           | T <sub>stg</sub> | -55 to 150 | °C   |  |

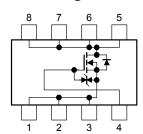
Note: For Notes 1 to 4, refer to the next page.

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.085 g (typ.)

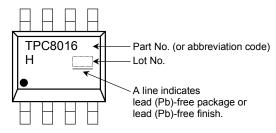
### **Circuit Configuration**



#### **Thermal Characteristics**

| Characteristic  | Symbol                 | Max  | Unit |
|---|------------------------|------|------|
| Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a) | R <sub>th (ch-a)</sub> | 65.8 | °C/W |
| Thermal resistance, channel to ambient (t = 10 s) (Note 2b)           | R <sub>th (ch-a)</sub> | 125  | °C/W |

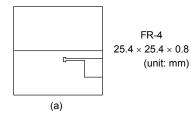
#### Marking (Note 5)

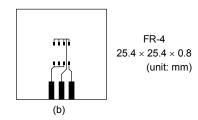


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



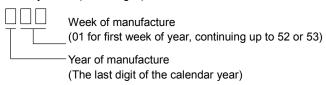


Note 3:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 0.5 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 15 A

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: • on the lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)



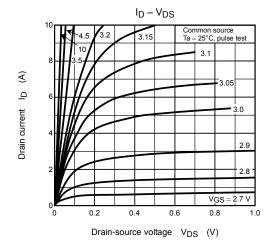
### Electrical Characteristics (Ta = 25°C)

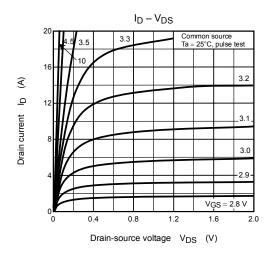
| Characteristic                                     |                 | Symbol               | Test Condition  | Min    | Тур. | Max | Unit |  |
|--|-----------------|----------------------|---|--------|------|-----|------|--|
| Gate leakage cur                                   | rent            | I <sub>GSS</sub>     | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$                       | _      | _    | ±10 | μА   |  |
| Drain cutoff curre                                 | ent             | I <sub>DSS</sub>     | V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V                           | _      | _    | 10  | μА   |  |
| Drain-source breakdown voltage                     |                 | V (BR) DSS           | $I_D = 10$ mA, $V_{GS} = 0$ V   | 30     | _    | _   | · V  |  |
| Diain-source bre                                   | akdowii voitage | V (BR) DSX           | $I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$                           | 15 — — |      | _   |      |  |
| Gate threshold vo                                  | oltage          | V <sub>th</sub>      | $V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$                             | 1.1    | _    | 2.3 | V    |  |
| Drain aguras ON                                    | raniatanaa      |                      | $V_{GS} = 4.5 \text{ V}, I_D = 7.5 \text{ A}$                           | _      | 5.5  | 7.5 |      |  |
| Drain-source ON-resistance                         |                 | R <sub>DS</sub> (ON) | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7.5 A                          |        | 3.7  | 5.7 | mΩ   |  |
| Forward transfer                                   | admittance      | Y <sub>fs</sub>      | $V_{DS} = 10 \text{ V}, I_D = 7.5 \text{ A}$                            | 12.5   | 25   | _   | S    |  |
| Input capacitance                                  | e               | C <sub>iss</sub>     |   |        | 2380 | _   |      |  |
| Reverse transfer capacitance                       |                 | C <sub>rss</sub>     | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz                | _      | 410  | _   | pF   |  |
| Output capacitance                                 |                 | C <sub>oss</sub>     |   |        | 980  | _   |      |  |
| Switching time                                     | Rise time       | t <sub>r</sub>       | VGS 10 V  | _      | 9.8  | _   | - ns |  |
|  | Turn-on time    | t <sub>on</sub>      |   | _      | 21   | _   |      |  |
|  | Fall time       | t <sub>f</sub>       |   | _      | 15   | _   |      |  |
|  | Turn-off time   | t <sub>off</sub>     | $V_{DD} \simeq 15 \text{ V}$ Duty $\leq 1\%$ , $t_W = 10 \mu\text{s}$   | _      | 60   | _   |      |  |
| Total gate charge<br>(gate-source plus gate-drain) |                 | Qg                   | $V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$ |        | 46   | _   |      |  |
|  |                 |                      | $V_{DD} \simeq 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 15 \text{ A}$  |        | 26   | _   | nC   |  |
| Gate-source charge 1                               |                 | Q <sub>gs1</sub>     | $V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$ | _      | 7.2  | _   |      |  |
| Gate-drain ("Miller") charge                       |                 | Q <sub>gd</sub>      |   |        | 12.2 | _   |      |  |
| Gate switch charge                                 |                 | $Q_{SW}$             |   | _      | 15.6 | _   |      |  |

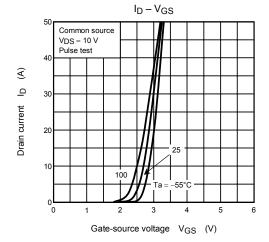
## Source-Drain Ratings and Characteristics (Ta = 25°C)

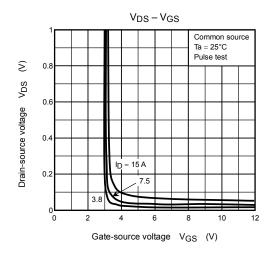
| Character               | istic |          | Symbol           | Test Condition                                | Min | Тур. | Max  | Unit |
|-------------------------|-------|----------|------------------|---|-----|------|------|------|
| Drain reverse current   | Pulse | (Note 1) | I <sub>DRP</sub> | _   | _   | _    | 60   | Α    |
| Forward voltage (diode) |       |          | V <sub>DSF</sub> | I <sub>DR</sub> = 15 A, V <sub>GS</sub> = 0 V | _   | _    | -1.2 | V    |

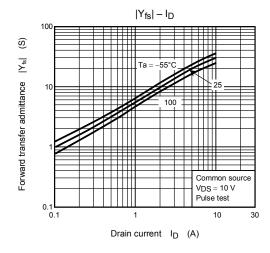
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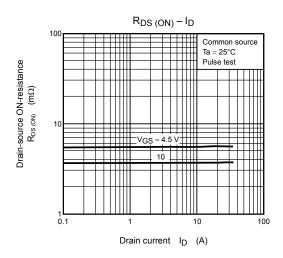




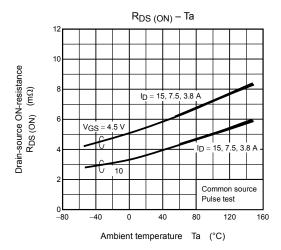


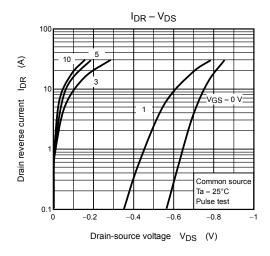


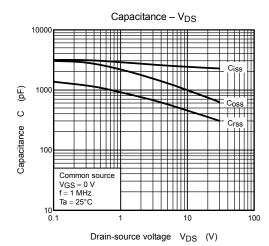


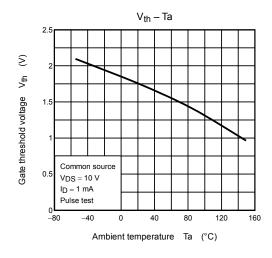


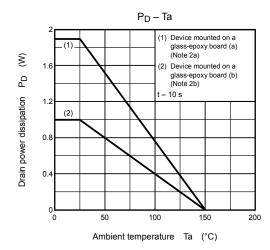
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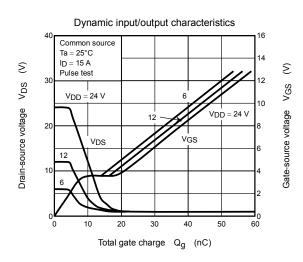




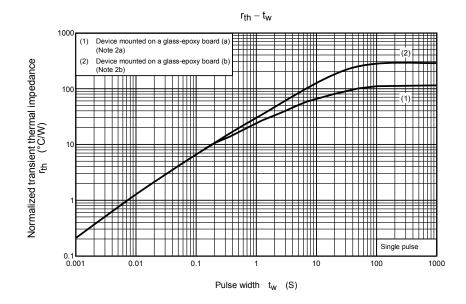


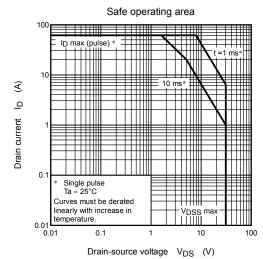






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